



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20220208000.1**

**Qualification of TIPI as an alternate Assembly site for select devices  
Change Notification / Sample Request**

**Date:** February 16, 2022  
**To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team  
SC Business Services

**20220208000.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
DP83848IVV/NOPB	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20220208000.1			<b>PCN Date:</b>	February 16, 2022																														
<b>Title:</b>	Qualification of TIPI as an alternate Assembly site for select devices																																		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services																																
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 16, 2022	<b>Estimated Sample Availability:</b>	Date provided at sample request																																
<b>Change Type:</b>																																			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site																														
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material																														
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process																														
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site																														
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials																														
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process																														
<b>PCN Details</b>																																			
<b>Description of Change:</b>																																			
Texas Instruments Incorporated is announcing the qualification of TIPI as an additional Assembly site for the select devices listed below. Construction differences are noted below:																																			
<table border="1"> <thead> <tr> <th>What</th> <th>ASEK</th> <th>TIEM</th> <th>TITL</th> <th>TIPI</th> </tr> </thead> <tbody> <tr> <td><b>Mold Compound</b></td> <td>SID#1800008161</td> <td>8095183</td> <td>4209640</td> <td><b>4222198</b></td> </tr> <tr> <td><b>Mount Compound</b></td> <td>SID#1400013111</td> <td>8001746</td> <td>4211470</td> <td><b>4211470</b></td> </tr> <tr> <td><b>Lead Finish</b></td> <td>Matte Sn</td> <td>Matte Sn</td> <td>NiPdAu</td> <td><b>NiPdAu</b></td> </tr> <tr> <td><b>Bond wire/diameter</b></td> <td>Au/1.0 mil</td> <td>Au/1.0 mil</td> <td>Cu/0.8 mil</td> <td><b>Cu/0.8 mil</b></td> </tr> <tr> <td><b>ECAT</b></td> <td>G3</td> <td>G3</td> <td>G4</td> <td><b>G4</b></td> </tr> </tbody> </table>						What	ASEK	TIEM	TITL	TIPI	<b>Mold Compound</b>	SID#1800008161	8095183	4209640	<b>4222198</b>	<b>Mount Compound</b>	SID#1400013111	8001746	4211470	<b>4211470</b>	<b>Lead Finish</b>	Matte Sn	Matte Sn	NiPdAu	<b>NiPdAu</b>	<b>Bond wire/diameter</b>	Au/1.0 mil	Au/1.0 mil	Cu/0.8 mil	<b>Cu/0.8 mil</b>	<b>ECAT</b>	G3	G3	G4	<b>G4</b>
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Upon expiration of this PCN, TI will combine lead free solutions in a single <b><a href="#">standard part number</a></b> , for example; <b><a href="#">DP83848CVV/NOPB</a></b> – can ship with both Matte Sn and NiPdAu.																																			
<b>Reason for Change:</b>																																			
Supply continuity																																			
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																																			
None																																			
<b>Impact on Environmental Ratings</b>																																			
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																																			
<b>RoHS</b>		<b>REACH</b>		<b>Green Status</b>																															
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change																															
<input type="checkbox"/>		<input type="checkbox"/>		<input type="checkbox"/>																															
<input type="checkbox"/>		<input type="checkbox"/>		<input type="checkbox"/>																															
<b>Changes to product identification resulting from this PCN:</b>																																			
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>																																
ASEK	ASF	TWN	Kaohsiung																																
TIEM	CU6	MYS	Melaka																																
TI Taiwan	TAI	TWN	Chung Ho, New Taipei City																																

<b>TIPI</b>	<b>PHI</b>	<b>PHL</b>	<b>Baguio City</b>
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Sample product shipping label (not actual product label)

 **TEXAS INSTRUMENTS**  
 MADE IN: Malaysia  
 2DC: 20:  

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

 OPT:  
 ITEM: 39  
**LBL: 5A (L)T0:1750**

  
 G4



(1P) SN74LS07NSR  
 0000 (D) 0336  
 (31T) LOT: 3959047  
 (4W) TKY (1T) 7523483SI2  
 (P)  
 (2P) REV: (V) 0033317  
 (20L) CS0: SHE (21L) CCO: USA  
 (22L) AS0: MLA (23L) ACO: MYS

G4: NiPdAu  
 G3: Matte Sn

**Product Affected:**

DP83848CVV/NOPB	DP83848EVVX/NOPB	DP83848IEVVX/NOPB	DP83848IVVX/NOPB
DP83848CVVX/NOPB	DP83848IEVV/NOPB	DP83848IVV/NOPB	DP83848IVVX/S7002477
DP83848EVV/NOPB			



**TI Information**  
 Selective disclosure

**Qualification Results**  
 Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration
PC	Preconditioning	(MSL3 @ 260C peak +/-0C)
CDM	ESD CDM	+/- 1000V
ED	Electrical Characterization	Per Datasheet Parameters
HAST	**Biased HAST	130C/85%RH/33.3 psia (96 Hrs.), Vddmax
HBM	ESD HBM	+/-4000V
LU	Latch-up	(per JESD78)-125C
MISC	Bond Pad Cratering Check	During MQ
MISC	Bond Pad Cratering Check	Post 500 Cycles
MQ	Manufacturability (Assembly)	(per mfg. Site specification)
MSL	Thermal Path Integrity	(level 3 @ 260C +/-0C)
PD	Physical Dimensions	(per mechanical drawing)
TC	**T/C -65C/150C	-65C/+150C (500, Cycles)
UHAST	**Unbiased HAST	130C/85%RH/33.3 psia (96 Hours)
WBP	Bond Pull	76 Wire, 3 units min
WBS	Ball Bond Shear	76 balls, 3 units min
XRAY	X-ray	(top side only)

Type	Test Name / Condition	Duration
BP	Post 500 TC Bond Pull	30 ball bonds, min. 5 units

- QBS: Qual By Similarity
- Qual Device DP83848EVV/NOPB is qualified at LEVEL3-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20210316-139150

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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